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### Dimensions

Chip Size	1812
L	4.52mm +/-0.3mm (0.178 in +/-0.012 in)
W	3.2mm +/-0.3mm (0.126 in +/-0.012 in)
T	2.79mm MAX (0.11 in MAX)
B	0.61mm +/-0.46mm (0.024 in +/-0.018 in)

### Packaging Specifications

Packaging	Waffle
Packaging Quantity	42

### General Information

Series	SMD MIL COG PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	No
Prop 65	<b>⚠ WARNING:</b> Cancer and reproductive harm - <a href="http://www.p65warnings.ca.gov">http://www.p65warnings.ca.gov</a> .
Termination	Solder Plated
Failure Rate	N/A
Qualifications	MIL-PRF-32535 M-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	0.033 uF
Capacitance Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.25% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	30.3 GOhms

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